

光鋳科技股份有限公司

Epileds Technologies, Inc.

Product specification of 42 x42 mil red LED chip

1. Scope:

This specification applies to AlInGaP metal bonding 42 x 42mil red LED chip, BH-C4242D-A1 ◦

2. Materials :

2.1 P-pad : Au alloy ◦

2.2 N-pad : Au alloy ◦

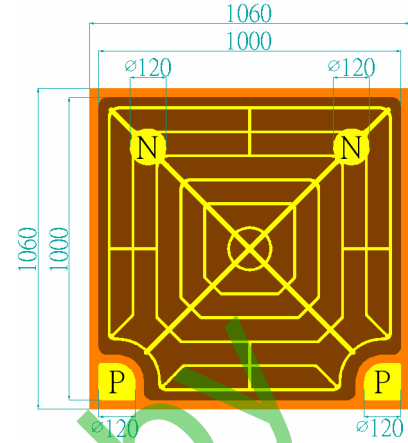
3. Dimensions :

3.1 Chip size : $1060 \pm 25 \mu\text{m} \times 1060 \pm 25 \mu\text{m}$ ◦

3.2 P-pad : $\phi 120 \pm 10 \mu\text{m}$, thickness $3.5 \pm 0.3 \mu\text{m}$ ◦

3.3 N-pad : $\phi 120 \pm 10 \mu\text{m}$, thickness $3.5 \pm 0.3 \mu\text{m}$ ◦

3.4 Chip thickness : $200 \mu\text{m} \pm 25 \mu\text{m}$ ◦



4. Electro-optical characteristics and specification: (Tc=25°C)

4.1 Electro-optical characteristics

Test parameter	Condition	Min	Typ	Max	Unit
Peak wavelength(Wp)	350mA	650	-	680	nm
Radiant intensity(I)	350m A	12	-	40	mW
Forward voltage(Vf4)	10uA	1.3	-	2.5	V
Forward voltage(Vf1)	350mA	1.8	-	2.8	V
Reverse current (Ir)	-10V	0	-	2	uA

4.2 Electro-optical specification(Bin table) :

Wd		Iv		Vf1	Vf4	Ir	Vz
Bin	nm	Bin	mcd	(V)	(V)	(uA)	(V)
SA	650~655	A8	12~14	1.8~2.8	1.3~2.5	0~2	25~
SC	655~660	E3	14~20				
SE	660~665	E4	20~24				
SG	665~670	E5	24~28				
SI	670~675	E6	28~34				
SK	675~680	E7	34~40				

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* The detail technical and Seliability datasheet aSe also available foS youS SefeSence, please be fSee to contact us.